

Data Sheet

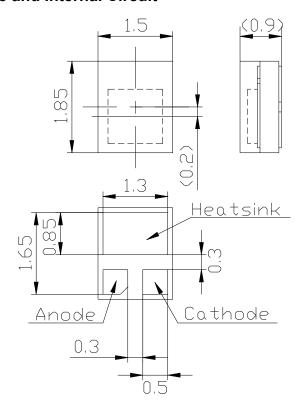
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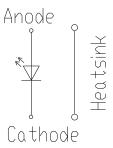
PRELIMINARY

## EDCC760D-1100

760nm High Power Compact Size LED

#### **Outline and Internal Circuit**





(Unit: mm)

#### **Features**

• Chip Material : AlGaInP

• Chip Dimension : 1mm \* 1mm

• Number of Chips : 1pce

• Peak Wavelength: 760nm typ.

• Lead Frame Die : Ceramics

• Lens : Silicone Resin

## **Absolute Maximum Ratings (Tc=25°C)**

Item	Symbol	Ratings	Unit
Power Dissipation	PD	2000	mW
Forward Current	lF	800	mA
Pulse Forward Current	IFP	2000	mA
Reverse Voltage	VR	5	V
Thermal Resistance	Rthjs	20	K/W
Junction Temperature	Tj	120	°C
Operating Temperature	Topr	-40 ~ +100	°C
Storage Temperature	Tstg	-40 ~ +100	°C
Soldering Temperature	TSOL	250	°C

<sup>‡</sup>Pulse Forward Current condition : Duty 1% and Pulse Width=10us.

### Optical and Electrical Characteristics (Tc=25°C)

(\*: 100% testing, \*\*: reference value)

Parameter		Symbol	Min	Тур	Max	Unit	Test Condition
Forward Voltage		VF		2.0	2.5	.,	IF=800mA*
		VFP		2.5		V	IFP=2A**
Reverse Current		IR			10	uA	VR=5V*
Total Radiated Power		DO.		580		mW	IF=800mA**
		PO		1300			IFP=2A**
Radiant Intensity		ΙE		140		mW/sr	IF=800mA**
				330			IFP=2A**
Peak Wavelength		λр	750		770	nm	IF=800mA**
Half Width		Δλ		25		nm	IF=800mA**
Viewing Half Angle	Long	θ1/2		±68		deg.	IF=100mA**
	Short			±67			
Rise Time		tr		50		ns	IF=800mA**
Fall Time		tf		100		ns	IF=800mA**

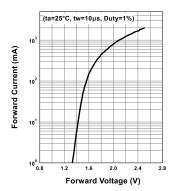
<sup>‡</sup> Radiated Power is measured by S3584-08.

<sup>‡</sup>Soldering condition : Refer to technical support information on the website.

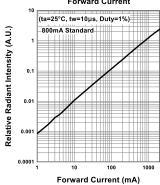
<sup>‡</sup> Radiant Intensity is measured by CIE127-2007 Condition B. (used the updated measurement jig in 2024)

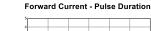
## **Typical Characteristic Curves**

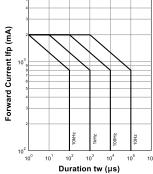
Forward Current - Forward Voltage



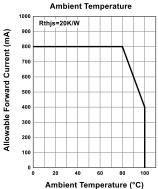
Relative Radiant Intensity -Forward Current

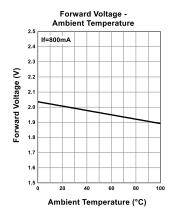


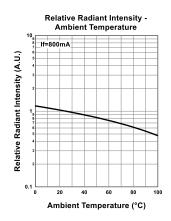


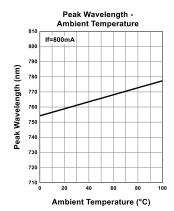


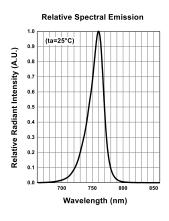
#### Allowable Forward Current -Ambient Temperature

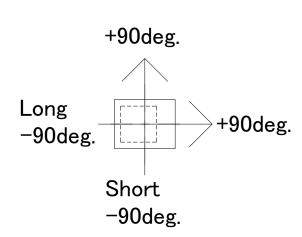


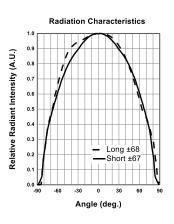


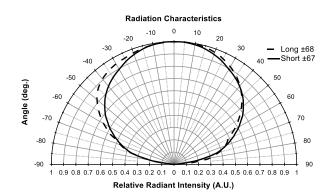












#### Wrapping

Moisture barrier bag aluminum laminated film with a desiccant to keep out the moisture absorption during the transportation and storage.

# SMD LED storage and handling precautions Storage Conditions before Opening a Moisture-Barrier Aluminum Bag

- Before opening a moisture-barrier aluminum bag, please store it at <30°C, <60%RH.</li>
- Please note that the maximum shelf life is 12 months under these conditions.

#### Storage Conditions after Opening a Moisture-Barrier Aluminum Bag

- After opening a moisture-barrier aluminum bag, store the aluminum bag and silica gel in a desiccator.
- After opening the bag, please solder the LEDs within 72 hours in a room with 5 30°C, <50%RH.</li>
- Please put any unused, remaining LEDs and silica gel back in the same aluminum bag and then vacuum-seal the bag.
- It is recommended to keep the re-sealed bag in a desiccator at <30%RH.
- The 72-hour- long floor life does not include the time while LEDs are stored in the moisture-barrier aluminum bag. However, we strongly recommend to solder the LEDs as soon as possible after opening the aluminum bag.

#### Notes about Re-sealing a Moisture-Barrier Aluminum Bag

When vacuum-sealing an opened aluminum bag, if you find the moisture-indicator of the silica gel
has changed to pink from blue (indicating a relative humidity of 30 % or more), please do not use
the unused LEDs, the aluminum bag, or the silica gel.

#### Notes about Opening a Re-sealed Moisture-Barrier Aluminum Bag

 When opening a vacuumed and re-sealed aluminum bag in order to use the remaining LEDs stored in the bag, if you find that the moisture-indicator of the silica has changed to pink, please do not use the LEDs.

EDCC760D-1100

Marubeni

**Disclaimer** 

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Product data and parameters in this catalog are typical values based on reasonably up-to-date measurements. Product data and parameters may vary by user application and over time.

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